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AMENDMENTS TO THE SPECIFICATION

The paragraph starting on page 5 at line 6 is amended as follows:

Underfill resin 20 22 is then injected between semiconductor chip 14 and substrate 11, and heat sink 21 is applied to the side of substrate 11 that is opposite the side on which semiconductor chip 14 is mounted. Underfill resin 20 22 adheres well to the surfaces of substrate 11 and semiconductor chip 14 because both surfaces have been effectively cleaned.